Sensitive Gate Triacs Silicon Bidirectional Triode Thyristors

... designed primarily for ac power switching. The gate sensitivity of these triacs permits the use of economical transistorized or integrated circuit control circuits, and it enhances their use in low-power phase control and load-switching applications.

- · Very High Gate Sensitivity
- Low On-State Voltage at High Current Levels
- · Glass-Passivated Chip for Stability
- Small, Rugged Thermopad Construction for Low Thermal Resistance, High Heat Dissipation and Durability

*Motorole preferred devices
se triacs
circuits,
SENSITIVE GATE TRIACs
2.5 AMPERES RMS
200 thru 600 VOLTS



T2322* T2323*

Series*

MT2 O MT1

MAXIMUM RATINGS (TJ = 25°C unless otherwise noted.)

Rating	Suffix	Symbol	Value	Unit
Peak Repetitive Off-State Voltage, Note 1 (T _J = 25 to 100°C, Gate Open) T2322, T2323	B D M	VDRM	200 400 600	Volts
RMS On-State Current (T _C = 70°C) (Full-Cycle Sine Wave 50 to 60 Hz)		IT(RMS)	2.5	Amps
Peak Non-Repetitive Surge Current (One Full Cycle, 60 Hz)		ITSM	25	Amps
Circuit Fusing (t = 8.3 ms)		i ² t	2.6	A ² s
Peak Gate Power (1 μs)		PGM	10	Watts
Average Gate Power (T _C = 60°C + 38.3 ms)		PG(AV)	0.15	Watt
Peak Gate Current (1 μs)		^I GM	0.5	Amp
Operating Junction Temperature Range		TJ	-40 to +110	°C
Storage Temperature Range		T _{stg}	-40 to +150	°C
Mounting Torque (6-32 Screw), Note 2		_	8	in. Ib.

Note 1. VDRM for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

2. Torque rating applies with use of torque washer (Shakeproof WD19523 or equivalent). Mounting Torque in excess of 6 in. lb. does not appreciably lower case-to-sink thermal resistance. Main terminal 2 and heat-sink contact pad are common.
For soldering purposes (either terminal connection or device mounting), soldering temperatures shall not exceed + 200°C, for 10 seconds. Consult factory for lead bending options.

T2322 • T2323 Series

THERMAL CHARACTERISTICS

Characteristic		Max	Unit	
Thermal Resistance, Junction to Case	R ₀ JC	3.5	°C/W	
Thermal Resistance, Junction to Ambient	R _Ø JA	60	°C/W	

 $\textbf{ELECTRICAL CHARACTERISTICS} \ (\textbf{T}_{C} = 25^{\circ} \text{C and either polarity of MT2 to MT1 voltage unless otherwise noted.})$

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Blocking Current (VD = Rated VDRM, Gate	Open) T _J = 25°C T _J = 100°C	DRM	=	 0.2	10 0.75	μA mA
Peak On-State Voltage* (ITM = 10 A)	T2323 Series T2322 Series	∨тм		1.7 1.7	2.6 2.2	Volts
MT2	nuous dc) Modes ((+), G(+); MT2(-), G(-) T2323 Series ((+), G(-); MT2(-),I G(+) T2323 Series	^I GT			10 25 40	mA
Gate Trigger Voltage (Continuous VD = 12 Vdc, $R_L = 30 \Omega$) ($V_D = V_{DRM}$, $R_L = 125 \Omega$)	$T_C = 25^{\circ}C$	v _{GT}	0.15	1	2.2	Volts
Holding Current (V _D = 12 V, I _{TM} = 150 m	A, Gate Open)	Ή	_	15	30	mA
Gate Controlled Turn-On Tin (V _D = Rated V _{DRM} , I _{TM}	· =	tgt	_	1.8	2.5	μs
Critical Rate-of-Rise of Off-S (V _D = Rated V _{DRM} , Expo	tate Voltage nential Waveform, T _C = 100°C)	dv/dt	10	100	_	V/μs
Critical Rate-of-Rise of Comr (VD = Rated VDRM, ITM di/dt = 1.26 A/ms, Gate U	= 3.5 A pk, Commutating	dv/dt(c)	1	4	_	V/μs

^{*}Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.